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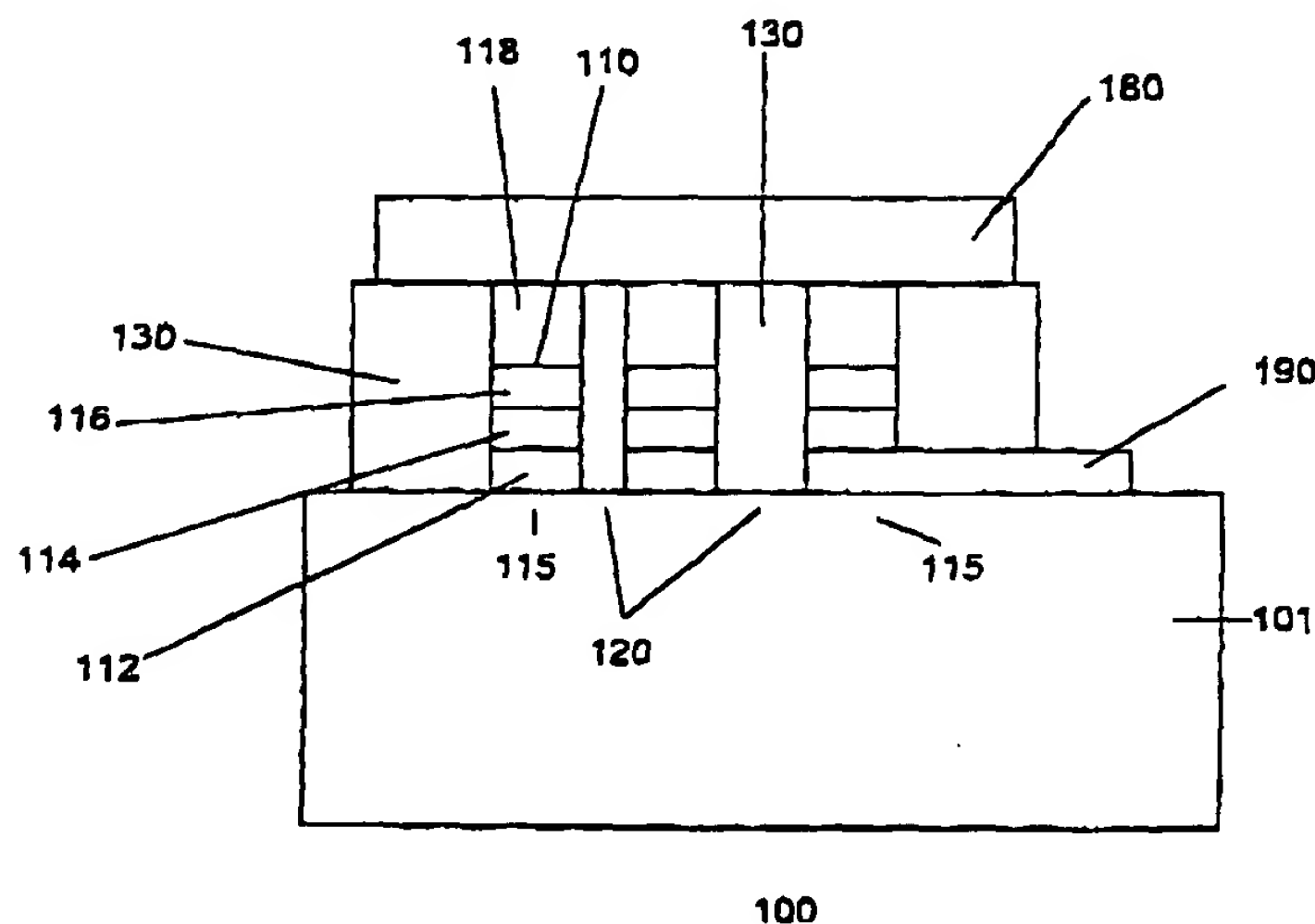
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(54) Title: ENCAPSULATION OF A DEVICE



(57) Abstract: An encapsulation for an electrical device (100) is disclosed. A cap support (130) is provided in the non-active regions (120) of the device (100) to prevent the package from contacting the active components (110) of the device due to mechanical stress induced in the package.

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Abstract

An encapsulation for an electrical device is disclosed. A cap support is provided in the non-active regions of the device to prevent the package from
5 contacting the active components of the device due to mechanical stress induced in the package.